PCN Number:	20171016001	P	CN Date:	Octo	ber 18	, 2017
Title: Datasheet for						
Customer Contact:	PCN Manager			De	ept:	Quality Services
Change Type:						
		Design			Wafer Bump Site	
		Data Sheet		<u> </u>		r Bump Material
		Part number change Fest Site		+		r Bump Process r Fab Site
		Test Process		+H		r Fab Materials
	0000		ΗH		r Fab Process	
Notification Details						
Description of Change:						
The product datasheet(s) is being updated as summarized below. The following change history provides further details.						
			5	CES651	G-JUNE 2	006-REVISED SEPTEMBER 2017
Changes from Revision F (I	December 2014) to Re	vision G				Page
Changed Device Information table						
Deleted GXU references throughout						
Added Junction temperature in the Absolute Maximum Ratings						
Reformatted Electrical Characteristics						
Added Basics of Voltage Translation to Related Documentation						
Added Receiving Notification of Documentation Updates and Community Resources						
The datasheet number	will be changing.	1				
Device Family		Change From:			Change To:	
TXS0104E		SCES651F			SCES651G	
These changes may be reviewed at the datasheet links provided.						
http://www.ti.com/product/TXS0104E						
Reason for Change:						
To accurately represent the device dimensions.						
Anticipated impact o			ality or Reli	abilit	y (pos	itive / negative):
No anticipated impact. This is a specification change announcement only. There are no changes						
to the actual device.						
Changes to product identification resulting from this PCN:						
None.						
Product Affected:						
TXS0104ED	TXS0104ED	1EDG4 TXS0104EI		DR		TXS0104EDRG4
TXS0104EPWR	TXS0104EPV	VRG4	TXS0104ERGYR TXS0104ERGYRG4			
TXS0104EYZTR	TXS0104EZ>	(UR				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com